ABSTRACT

A photosensitive adhesive resin composition includes (A) a compound having a hydroxyl group or a carboxyl group, and a (meth)acryloyl group, (B) a resin which cures with the compound (A) by thermal treatment, (C) a compound having a (meth)acryloyl group and not having a hydroxyl group and a carboxyl group, (D) a phenol resin or a phenol compound, and (E) a photoactive compound. The photosensitive adhesive resin composition has excellent developability, and is used for producing a spacer formed between a transparent substrate and a substrate on which a semiconductor element is formed. An adhesive film and a light-receiving device are produced using the photosensitive adhesive resin composition.